

- Organization . . . 16K × 8
- Processed to MIL-STD-883, Class B
- Single 5-V Power Supply
- Pin-Compatible With Existing 64K and 128K EPROMs
- All Inputs/Outputs Fully TTL-Compatible
- Max Access/Min Cycle Times

$V_{CC} \pm 5\%$	$V_{CC} \pm 10\%$	
'27C128-120		120 ns
	'27C128-15	150 ns
	'27C128-17	170 ns
	'27C128-20	200 ns
	'27C128-25	250 ns
- HVCMOS Technology
- 3-State Output Buffer
- Low Power Dissipation
 - Active . . . 138 mW Worst Case
 - Standby . . . 1.7 mW Worst Case

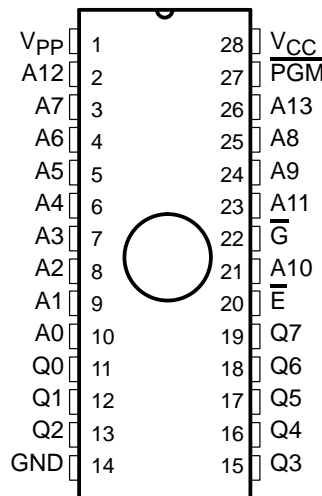
(CMOS-Input Levels)
- 400-mV Minimum DC Noise Immunity With Standard TTL Loads
- Military Operating Temperature Range
 - 55°C to 125°C

description

The SMJ27C128 series is a set of 131 072-bit, ultraviolet-light erasable, electrically programmable read-only memories. These devices are fabricated using HVCMOS technology for high speed and simple interfacing with MOS and bipolar circuits. All inputs (including program data inputs) can be driven by Series 54 TTL circuits without the use of external pullup resistors. The data outputs are three-state for connecting multiple devices to a common bus. The SMJ27C128 is pin-compatible with 28-pin 128K ROMs and EPROMs. They are offered in a 600-mil dual-in-line ceramic package (J suffix) rated for operation from –55°C to 125°C.

Since these EPROMs operate from a single 5-V supply (in the read mode), they are ideal for use in microprocessor-based systems. One other (12.5 V) supply is needed for programming, but all programming signals are TTL-level. These devices are programmable by either Fast or SNAP! Pulse programming algorithms. The Fast programming algorithm uses a V_{PP} of 12.5 V and a V_{CC} of 6 V for a nominal programming time of two minutes. The SNAP! Pulse programming algorithm uses a V_{PP} of 13.0 V and a V_{CC} of 6.5 V for a nominal programming time of two seconds. For programming outside the system, existing EPROM programmers can be used. Locations can be programmed singly, in blocks, or at random.

**J PACKAGE
(TOP VIEW)**



PIN NOMENCLATURE	
A0–A13	Address Inputs
\overline{E}	Chip Enable, Power Down
\overline{G}	Output Enable
GND	Ground
PGM	Program
Q0–Q7	Outputs
V_{CC}	5-V Power Supply
V_{PP}	12–13-V Power Supply

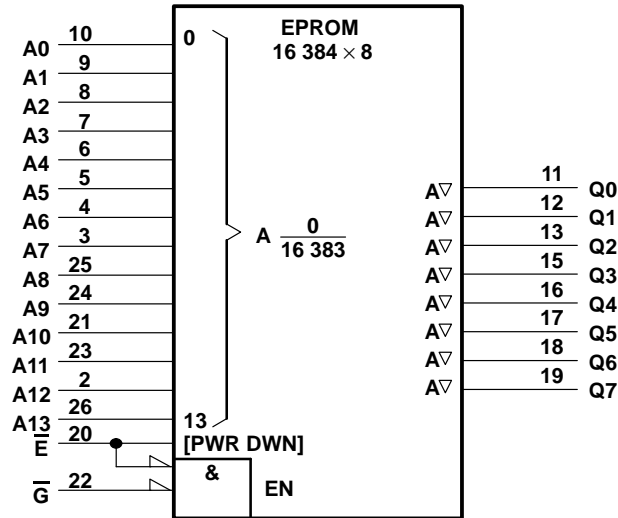
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SMJ27C128 131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

operation

The seven modes of operation for the SMJ27C128 are listed in the following table. The read mode requires a single 5-V supply. All inputs are TTL-level except for V_{PP} during programming (12.5 V for Fast or 13 V for SNAP! Pulse) and 12 V on A9 for signature mode.

FUNCTION (PINS)	MODE							
	READ	OUTPUT DISABLE	STANDBY	PROGRAMMING	VERIFY	PROGRAM INHIBIT	SIGNATURE MODE	
\bar{E} (20)	V_{IL}	V_{IL}	V_{IH}	V_{IL}	V_{IL}	V_{IH}	V_{IL}	
\bar{G} (22)	V_{IL}	V_{IH}	X^\ddagger	V_{IH}	V_{IL}	X	V_{IL}	
\overline{PGM} (27)	V_{IH}	V_{IH}	X	V_{IL}	V_{IH}	X	V_{IH}	
V_{PP} (1)	V_{CC}	V_{CC}	V_{CC}	V_{PP}	V_{PP}	V_{PP}	V_{CC}	
V_{CC} (28)	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	
A9 (24)	X	X	X	X	X	X	V_H^\S V_H^\S	
A0 (10)	X	X	X	X	X	X	V_{IL} V_{IH}	
Q0–Q7 (11–13, 15–19)	Data Out	Hi-Z	Hi-Z	Data In	Data Out	Hi-Z	CODE	
							MFG	DEVICE
							97	83

‡ X can be V_{IL} or V_{IH} .

§ $V_H = 12 V \pm 0.5 V$.

read/output disable

When the outputs of two or more SMJ27C128s are connected in parallel on the same bus, the output of any device in the circuit can be read without interference from the outputs of competing devices. To read the output of the selected SMJ27C128, a low-level signal is applied to the \bar{E} and \bar{G} pins. All other devices in the circuit should have their outputs disabled by the application of a high-level signal to one of these pins. Output data is accessed at pins Q0 through Q7.

latchup immunity

Latchup immunity on the SMJ27C128 is achieved by the application of a minimum of 250 mA on all inputs and outputs. This current provides latchup immunity beyond any potential transients at the PC-board level when the devices are interfaced to industry-standard TTL or MOS logic devices. Input/output layout approach controls latchup without compromising performance or packing density.

For more information, see application report SMLA001, *Design Considerations; Latchup Immunity of the HVC MOS EPROM Family*, available through TI Field Sales Offices.

powerdown

Active I_{CC} supply current can be reduced from 25 mA to 500 μ A (TTL-level inputs) or 300 μ A (CMOS-level inputs) by applying a high input signal to the \bar{E} pin. In this mode all outputs are in the high-impedance state.

erasure

Before programming, the SMJ27C128 is erased by exposing the chip through the transparent lid to a high intensity ultraviolet light (wavelength 2537 Å). EPROM erasure before programming is necessary to assure that all bits are in the logic 1 (high) state. Logic lows are programmed into the desired locations. A programmed logic low can be erased only by ultraviolet light. The recommended minimum exposure dose (UV intensity \times exposure time) is 15 W•s/cm². A typical 12 mW/cm², filterless UV lamp erases the device in 21 minutes. The lamp should be located about 2.5 cm above the chip during erasure. After erasure, all bits are in the high state. It should be noted that normal ambient light contains the correct wavelength for erasure. Therefore, when using the SMJ27C128, the window should be covered with an opaque label.

SNAP! Pulse programming

The 128K EPROM can be programmed using the TI SNAP! Pulse programming algorithm illustrated by the flowchart in Figure 1. The TI SNAP! Pulse programming algorithm can reduce programming time to two seconds. Actual programming time varies as a function of the programming used.

Data is presented in parallel (eight bits) on pins Q0 to Q7. Once addresses and data are stable, \overline{PGM} is pulsed.

The SNAP! Pulse programming algorithm uses initial pulses of 100 μ s followed by a byte verification to determine when the addressed byte has been successfully programmed. Up to ten 100- μ s pulses per byte are provided before a failure is recognized.

The programming mode is achieved when $V_{PP} = 13$ V, $V_{CC} = 6.5$ V, $\bar{G} = V_{IH}$, and $\bar{E} = V_{IL}$. More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order. When the SNAP! Pulse programming routine is complete, all bits are verified with $V_{CC} = V_{PP} = 5$ V.

Fast programming

The 128K EPROM can be programmed using the Fast programming algorithm illustrated by the flowchart in Figure 2. During Fast programming, data is presented in parallel (eight bits) on pins Q0 through Q7. Data is presented in parallel (eight bits) on pins Q0 to Q7. Once addresses and data are stable, \overline{PGM} is pulsed.

SMJ27C128

131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

Fast programming (continued)

The programming mode is achieved when $V_{PP} = 12.5$ V, $V_{CC} = 6$ V, $\overline{G} = V_{IH}$, $\overline{PGM} = V_{IL}$, and $\overline{E} = V_{IL}$. More than one SMJ27C128 can be programmed when the devices are connected in parallel. Locations can be programmed in any order.

Programming uses two types of programming pulses: prime and final. The length of the prime pulse is 1 millisecond; this pulse is applied up to 25 times. After each prime pulse, the byte being programmed is verified. If the correct data is read, the final programming pulse is applied; if correct data is not read, an additional 1 millisecond pulse is applied up to 25 times. The final programming pulse is 3X long. This sequence of programming and verification is performed at $V_{CC} = 6$ V and $V_{PP} = 12.5$ V. When the full Fast programming routine is complete, all bits are verified with $V_{CC} = V_{PP} = 5$ V (see Figure 2).

program inhibit

Programming can be inhibited by maintaining a high level input on the \overline{E} or \overline{PGM} pin.

program verify

Programmed bits can be verified with $V_{PP} = 12.5$ V when $\overline{G} = V_{IL}$, $\overline{E} = V_{IL}$, and $\overline{PGM} = V_{IH}$.

signature mode

The signature mode provides access to a binary code identifying the manufacturer and type. This mode is activated when A9 (pin 24) is forced to 12 V \pm 0.5 V. Two identifier bytes are accessed by A0 (pin 10); i.e., $A0 = V_{IL}$ accesses the manufacturer code, which is output on Q0–Q7; $A0 = V_{IH}$ accesses the device code, which is output on Q0–Q7. All other addresses must be held at V_{IL} . Each byte possesses odd parity on bit Q7. The manufacturer code for these devices is 97, and the device code is 83.



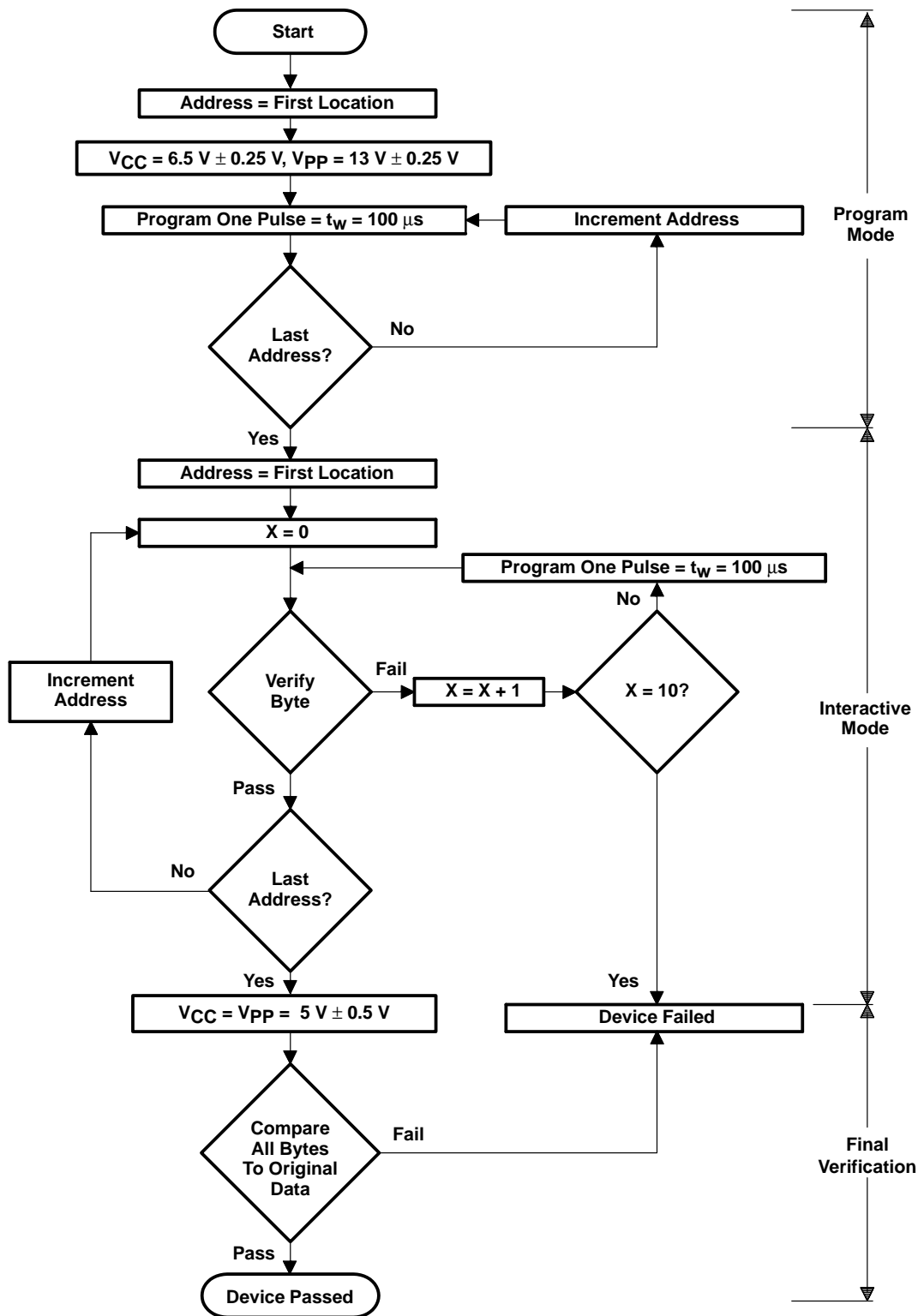


Figure 1. SNAP! Pulse Programming Flowchart

SMJ27C128 131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

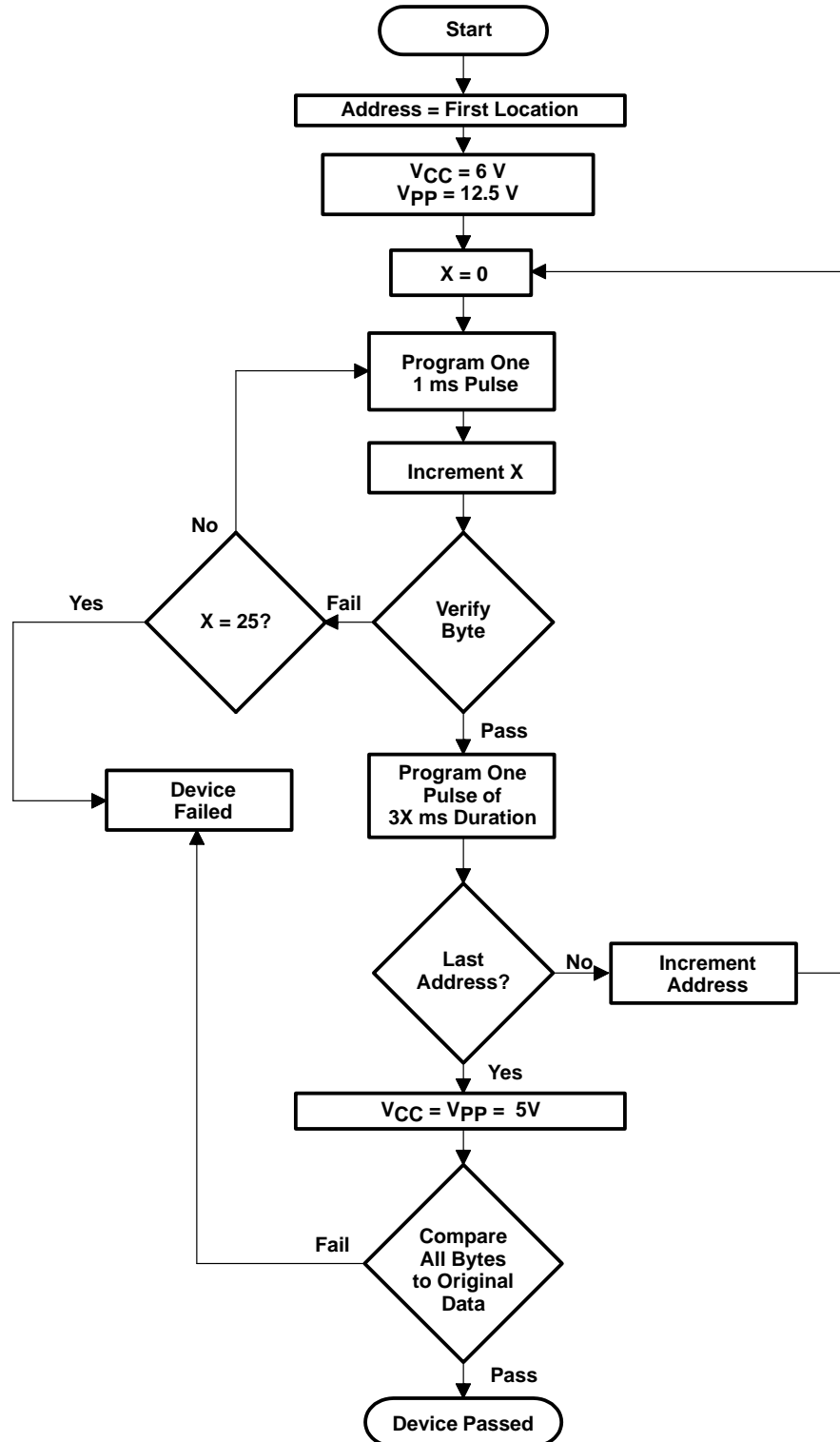


Figure 2. Fast Programming Flowchart

SMJ27C128

131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.6 V to 7 V
Supply voltage range, V_{PP} (see Note 1)	–0.6 V to 14 V
Input voltage range (see Note 1), All inputs except A9	–0.6 V to 6.5 V
A9	–0.6 V to 13.5 V
Output voltage range (see Note 1)	–0.6 V to $V_{CC} + 1$ V
Minimum operating free-air temperature, T_A	–55° C
Maximum operating case temperature	125° C
Storage temperature range, T_{stg}	–65° C to 150° C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

recommended operating conditions

		'27C128-120			'27C128-15 '27C128-17 '27C128-20 '27C128-25			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX			
V_{CC}	Supply voltage	Read mode (see Note 2)	4.75	5	5.25	4.5	5	5.5	V	
		Fast programming algorithm	5.75	6	6.25	5.75	6	6.25	V	
		SNAP! Pulse programming algorithm	6.25	6.50	6.75	6.25	6.5	6.75	V	
V_{PP}	Supply voltage	Read mode (see Note 3)	$V_{CC} - 0.6$		$V_{CC} + 0.6$	$V_{CC} - 0.6$		$V_{CC} + 0.6$	V	
		Fast programming algorithm	12	12.5	13	12	12.5	13	V	
		SNAP! Pulse programming algorithm	12.75	13	13.25	12.75	13	13.25	V	
V_{IH}	High-level input voltage	TTL	2		$V_{CC} + 1$		2		$V_{CC} + 1$	V
		CMOS	$V_{CC} - 0.2$		$V_{CC} + 1$	$V_{CC} - 0.2$		$V_{CC} + 1$		V
V_{IL}	Low-level input voltage	TTL	–0.5		0.8		–0.5		0.8	V
		CMOS	–0.5		0.2		–0.5		0.2	V
T_A	Operating free-air temperature	–55			–55			°C		
T_C	Operating case temperature	125			125			°C		

- NOTES: 2. V_{CC} must be applied before or at the same time as V_{PP} and removed after or at the same time as V_{PP} . The device must not be inserted into or removed from the board when V_{PP} or V_{CC} is applied.
3. V_{PP} can be connected to V_{CC} directly (except in the program mode). V_{CC} supply current in this case is $I_{CC} + I_{PP}$.



SMJ27C128

131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	I _{OH} = -400 mA	2.4			V
V _{OL}	Low-level output voltage	I _{OL} = 2.1 mA			0.4	V
I _I	Input current (leakage)	V _I = 0 V to 5.5 V			±1	μA
I _O	Output current (leakage)	V _O = 0 V to V _{CC}			±1	μA
I _{PP1}	V _{PP} supply current	V _{PP} = V _{CC} = 5.5 V			100	μA
I _{PP2}	V _{PP} supply current (during program pulse) (see Note 4)	V _{PP} = 13 V		35	50	mA
I _{CC1}	V _{CC} supply current (standby)	TTL-input level	V _{CC} = 5.5 V, $\bar{E} = V_{IH}$		500	μA
		CMOS-input level	V _{CC} = 5.5 V, $\bar{E} = V_{CC}$		300	μA
I _{CC2}	V _{CC} supply current (active)	V _{CC} = 5.5 V, $\bar{E} = V_{IL}$, t _c = minimum cycle time, outputs open		10	25	mA

† Typical values are at T_A = 25°C and nominal voltages.

NOTE 4: This parameter has been characterized at 25°C and is not tested.

capacitance over recommended ranges of supply voltage and operating free-air temperature, f = 1 MHz (see Note 5)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
C _i	Input capacitance	V _I = 0 V, f = 1 MHz		6	10	pF
C _o	Output capacitance	V _O = 0 V, f = 1 MHz		8	14	pF

† Typical values are at T_A = 25°C and nominal voltages.

NOTE 5: Capacitance measurements are made on sample basis only.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Notes 4 and 5)

PARAMETER	TEST CONDITIONS (SEE NOTES 4 AND 5)	'27C128-120		'27C128-15		'27C128-17		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _{a(A)}	Access time from address	120		150		170		ns
t _{a(E)}	Access time from chip enable	120		150		170		ns
t _{en(G)}	Output enable time from \bar{G}	50		70		70		ns
t _{dis}	Output disable time from \bar{G} or \bar{E} , whichever occurs first†	0	50	0	50	0	50	ns
t _{v(A)}	Output data valid time after change of address, \bar{E} , or \bar{G} , whichever occurs first†	0		0		0		ns

PARAMETER	TEST CONDITIONS (SEE NOTES 4 AND 5)	'27C128-20		'27C128-25		UNIT
		MIN	MAX	MIN	MAX	
t _{a(A)}	Access time from address	200		250		ns
t _{a(E)}	Access time from chip enable	200		250		ns
t _{en(G)}	Output enable time from \bar{G}	75		100		ns
t _{dis}	Output disable time from \bar{G} or \bar{E} , whichever occurs first†	0	60	0	60	ns
t _{v(A)}	Output data valid time after change of address, \bar{E} , or \bar{G} , whichever occurs first†	0		0		ns

† Value calculated from 0.5 V delta to measured level. This parameter is only sampled and not production-tested.



SMJ27C128

131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

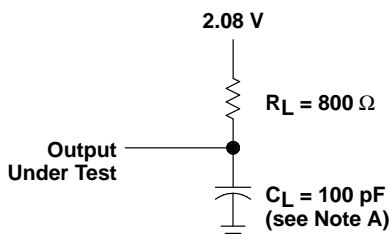
SGMS006F – AUGUST 1986 – REVISED JUNE 1995

recommended timing requirements for programming: $V_{CC} = 6\text{ V}$ and $V_{PP} = 12.5\text{ V}$ (Fast) or $V_{CC} = 6.5$ and $V_{PP} = 13\text{ V}$ (SNAP! Pulse), $T_A = 25^\circ\text{C}$ (see Note 6)

		MIN	NOM	MAX	UNIT		
t_{dis}	Disable time, output from \overline{G} (see Note 7)	0		130	ns		
t_{enG}	Enable time, output from \overline{G}			150	ns		
$t_{h(A)}$	Hold time, address	0			μs		
$t_{h(D)}$	Hold time, data	2			μs		
$t_{w(IPGM)}$	Pulse duration, initial program	Fast programming algorithm		0.95	1	1.05	ms
		SNAP! Pulse programming algorithm		95	100	105	μs
$t_{w(FPGM)}$	Pulse duration, final	Fast programming only		2.85	78.75	ms	
$t_{su(A)}$	Setup time, address	2			μs		
$t_{su(G)}$	Setup time, \overline{G}	2			μs		
$t_{su(D)}$	Setup time, data	2			μs		
$t_{su(VPP)}$	Setup time, V_{PP}	2			μs		
$t_{su(VCC)}$	Setup time, V_{CC}	2			μs		
$t_{su(E)}$	Setup time, \overline{E}	2			μs		

- NOTES: 6. For all switching characteristics and timing measurements input pulse levels are 0.4 V to 2.4 V. Timing measurements are made at 2.0 V for logic high and 0.8 V for logic low for both inputs and outputs.
 7. Common test conditions apply for t_{dis} except during programming.

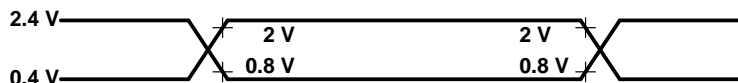
PARAMETER MEASUREMENT INFORMATION



NOTE A: C_L includes probe and fixture capacitance.

Figure 3. Output Load Circuit

AC testing input/output wave forms



AC testing inputs are driven at 2.4 V for logic high and 0.4 V for logic low. Timing measurements are made at 2 V for logic high and 0.8 V for logic low for both inputs and outputs.

SMJ27C128 131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

SGMS006F – AUGUST 1986 – REVISED JUNE 1995

PARAMETER MEASUREMENT INFORMATION

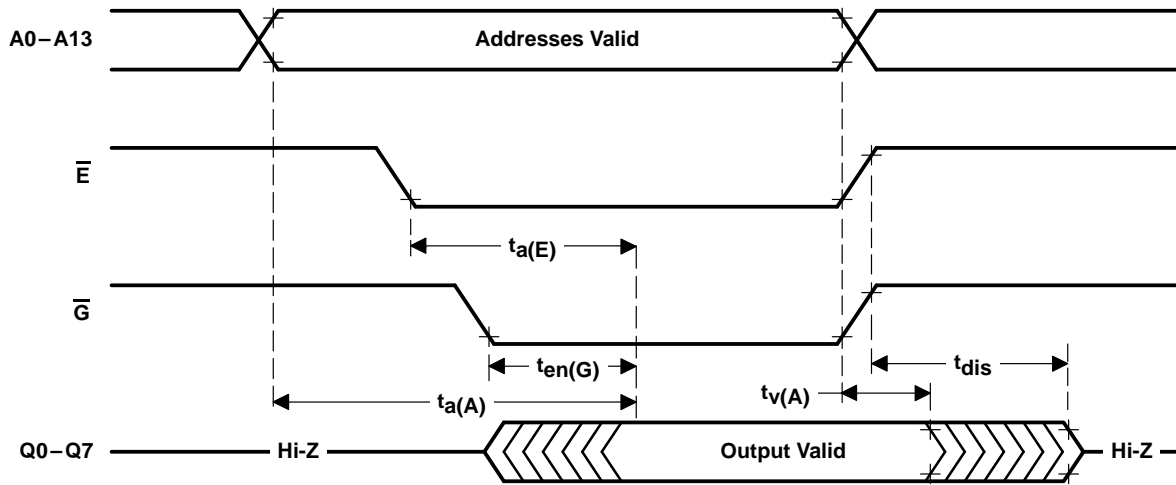


Figure 4. Read-Cycle Timing

PARAMETER MEASUREMENT INFORMATION

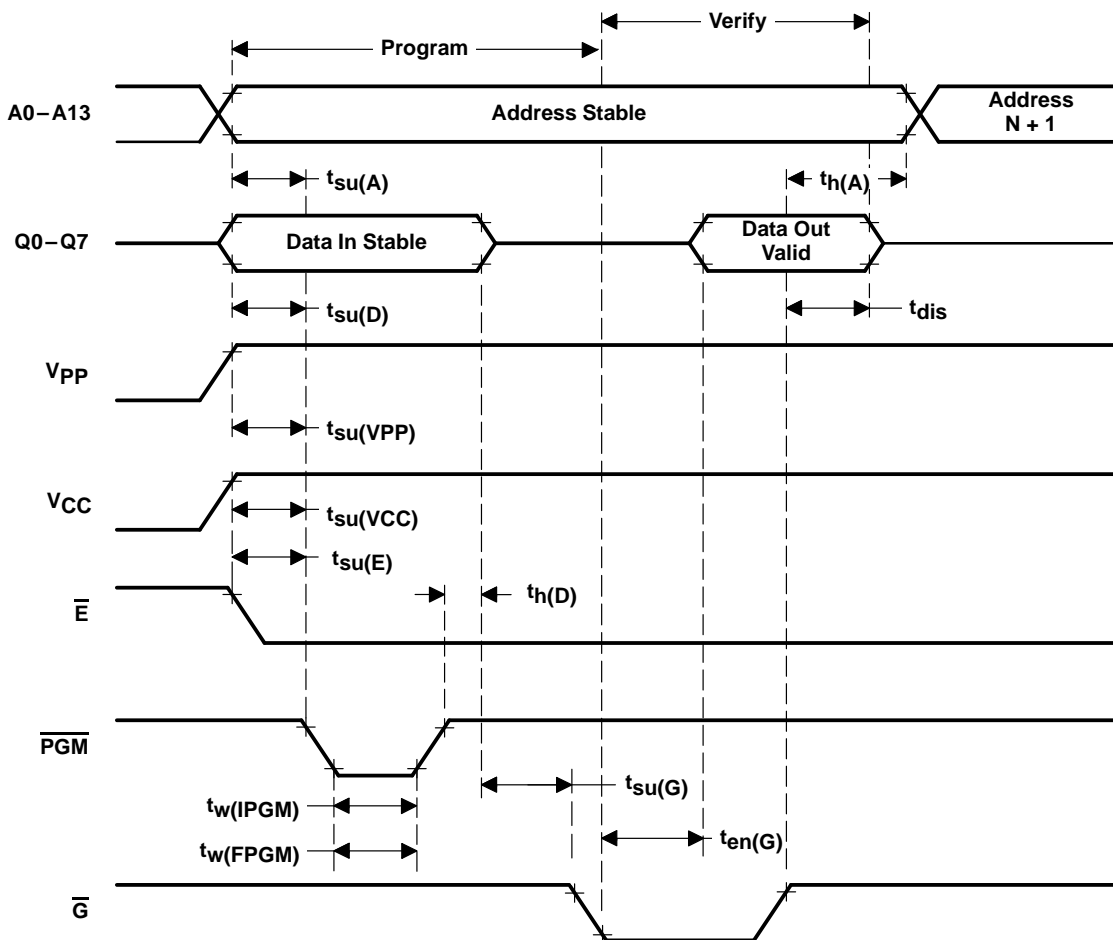


Figure 5. Program-Cycle Timing

SMJ27C128 131072-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY

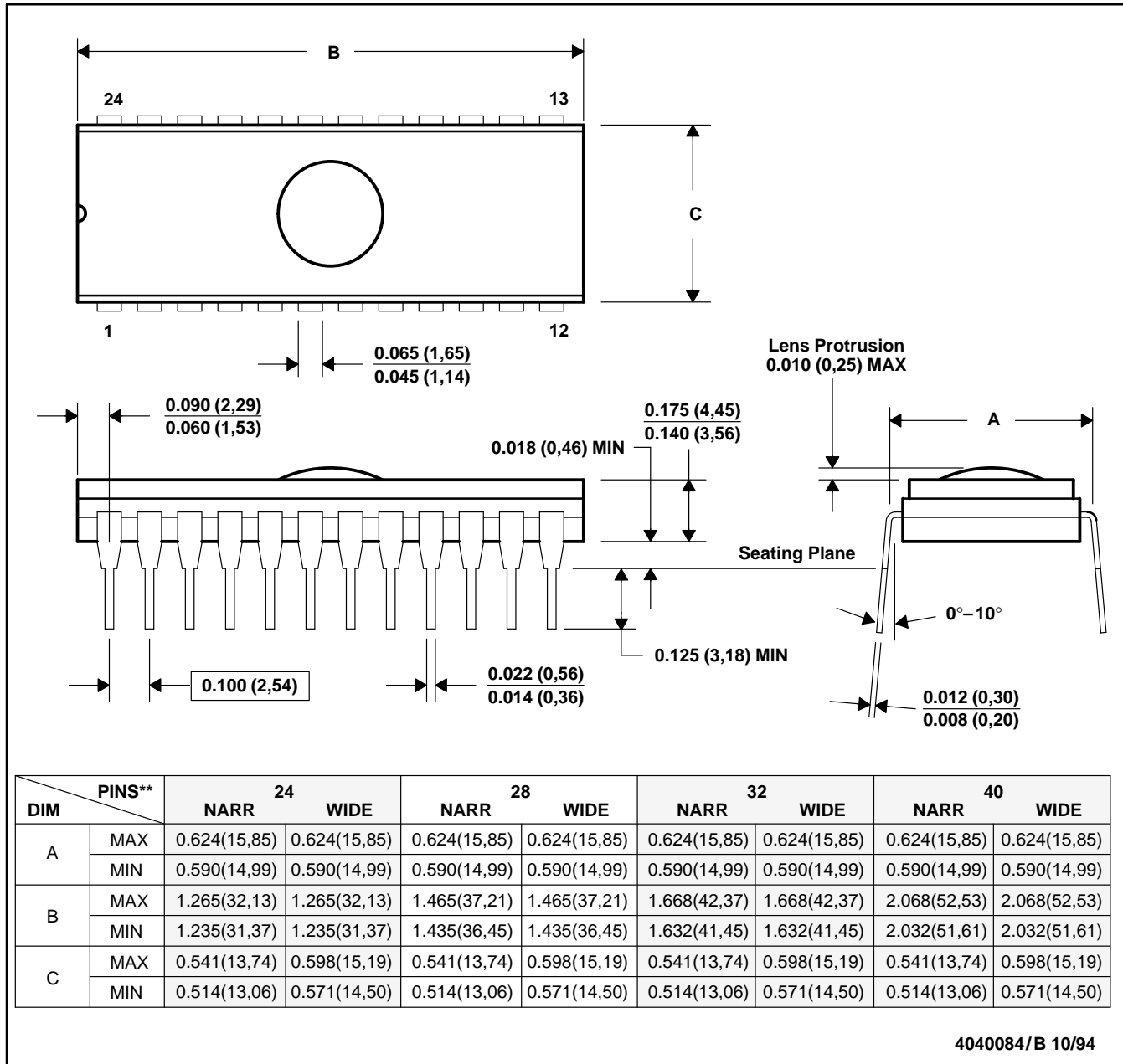
SGMS006F – AUGUST 1986 – REVISED JUNE 1995

MECHANICAL DATA

J (R-CDIP-T**)

CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE

24 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only

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